

L Number	Hits	Search Text	DB	Time stamp
-	114427	electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:03
-	251638	seed\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:05
-	1837550	fill\$4 or refill\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 10:12
-	1159899	copper or cu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 09:02
-	697397	photoresist or resist or photosensitive or photo adj2 sensitive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 12:58
-	1173993	wiring or interconnect\$4 or inter adj2 connect\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 09:04
-	392748	harden\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 09:42
-	5058080	groove or trench or hole or aperture or opening	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:04
-	7713	(copper or cu) with (fill\$4 or refill\$4) with (groove or trench or hole or aperture or opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 10:14
-	13795	seed\$4 with (groove or trench or hole or aperture or opening)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 10:14
-	597	((electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) same ((copper or cu) with (fill\$4 or refill\$4) with (groove or trench or hole or aperture or opening)) same (seed\$4 with (groove or trench or hole or aperture or opening))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 10:17
-	276	((electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) same ((copper or cu) with (fill\$4 or refill\$4) with (groove or trench or hole or aperture or opening)) same (seed\$4 with (groove or trench or hole or aperture or opening))) and (photoresist or resist or photosensitive or photo adj2 sensitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 14:28

-	114427	electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 12:58
-	995720	photoresist or resist or photosensitive or photo adj2 sensitive or polymeric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 12:59
-	2422381	(photoresist or resist or photosensitive or photo adj2 sensitive or polymeric) or polymer or polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:00
-	1175302	hard or hardern\$4 or cure\$1 or curing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:02
-	107409	((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric) or polymer or polyimide) with (hard or hardern\$4 or cure\$1 or curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:03
-	114427	electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:04
-	5058080	groove or trench or hole or aperture or opening	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:04
-	251638	seed\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:05
-	2413	(electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) same (groove or trench or hole or aperture or opening) same seed\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:07
-	12579	(metal\$4 or conduct\$4 or wire or wiring or stud) with (pattern\$3) with (remov\$3) with ((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric) or polymer or polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 14:12
-	164	((electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) same (groove or trench or hole or aperture or opening) same seed\$4) and ((metal\$4 or conduct\$4 or wire or wiring or stud) with (pattern\$3) with (remov\$3) with ((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric) or polymer or polyimide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:13

-	82	((electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) same (groove or trench or hole or aperture or opening) same seed\$4) and ((metal\$4 or conduct\$4 or wire or wiring or stud) with (pattern\$3) with (remov\$3) with ((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric) or polymer or polyimide))) and (hard or hardern\$4 or cure\$1 or curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:40
-	4707	438/618.ccls. or 438/622.ccls. or 438/623.ccls. or 438/637.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:40
-	453	(438/618.ccls. or 438/622.ccls. or 438/623.ccls. or 438/637.ccls.) and (electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) and seed\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 13:40
-	1492	(metal\$4 or conduct\$4 or wire or wiring or stud) with (pattern\$3) with (liftoff or lift\$3 adj2 off) with ((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric) or polymer or polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 14:13
-	10	((electroplat\$4 or electro adj2 plat\$4 or electrodeposit\$4 or electrol\$8 near3 deposit\$4 or electrochemical\$2 near3 deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) same (groove or trench or hole or aperture or opening) same seed\$4) and ((metal\$4 or conduct\$4 or wire or wiring or stud) with (pattern\$3) with (liftoff or lift\$3 adj2 off) with ((photoresist or resist or photosensitive or photo adj2 sensitive or polymeric) or polymer or polyimide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 14:14